- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V<sub>CC</sub> and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

### description

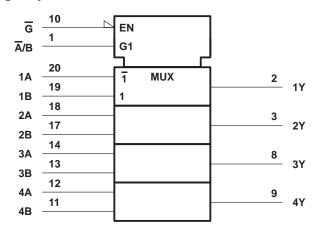
This data selector/multiplexer contains inverters and drivers to supply full data selection to the four output gates. A separate strobe  $(\overline{G})$  input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 74AC11157 provides true data.

The 74AC11157 is characterized for operation from –40°C to 85°C.

#### **FUNCTION TABLE**

	INPU	OUTPUT		
G	Ā/B	Α	В	Υ
Н	Х	Χ	Χ	L
L	L	L	Χ	L
L	L	Н	X	Н
L	Н	Χ	L	L
L	Н	Χ	Н	Н

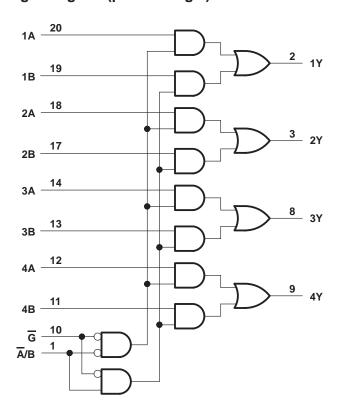
# logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### **DW OR N PACKAGE** (TOP VIEW) $\overline{A}/B$ 20 1 1A 19 1B 1Y **∏** 2Y 🛛 3 18 D 2A GND 4 17 2B GND [] 5 16 VCC 15 V<sub>CC</sub> GND I 6 GND 17 14 🛮 3A 3Y 🛮 8 13 3B 4Y **∏** 9 12**∏** 4A G 11 **∏** 4B

### logic diagram (positive logic)



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Storage temperature range	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		3	5	5.5	V
		V <sub>CC</sub> = 3 V	2.1			
٧IH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			V
		V <sub>CC</sub> = 5.5 V	3.85			
		V <sub>CC</sub> = 3 V			0.9	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35	V
		V <sub>CC</sub> = 5.5 V			1.65	
VI	Input voltage		0		VCC	V
Vo	Output voltage		0		VCC	V
		V <sub>CC</sub> = 3 V			-4	
lOH	High-level output current	V <sub>CC</sub> = 4.5 V			-24	mA
		V <sub>CC</sub> = 5.5 V			-24	
		V <sub>CC</sub> = 3 V			12	
lOL	Low-level output current	V <sub>CC</sub> = 4.5 V			24	mA
		V <sub>CC</sub> = 5.5 V			24	
Δt/Δν	Input transition rise or fall rate		0		10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST COMPLIANCE	VCC	TA = 25°C					
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	UNIT
			2.9			2.9		
	$I_{OH} = -50 \mu\text{A}$	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
VOH	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		V
		4.5 V	3.94			3.8		
	$I_{OL} = -24 \text{ mA}$		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	Ι <sub>ΟL</sub> = 50 μΑ	3 V			0.1		0.1	
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
VOL	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44	V
	In. 24 mA	4.5 V			0.36		0.44	
	I <sub>OL</sub> = 24 mA				0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
II	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		3.5	·		·	pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T <sub>A</sub> = 25°C					
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>	A D	V	1.8	6.2	8.5	1.8	9.5	
<sup>t</sup> PHL	A or B	Y	2.6	8.3	11.1	2.6	12.5	ns
t <sub>PLH</sub>		V	1.9	6.8	8.9	1.9	10	
<sup>t</sup> PHL	Ā/B	Y	2.7	8.7	11.4	2.7	12.9	ns
t <sub>PLH</sub>	G	Y	1.6	6	8.6	1.6	9.2	
<sup>t</sup> PHL	G		2.8	8.6	11.2	2.8	12.3	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

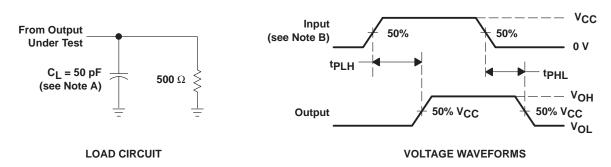
DADAMETED	FROM	то	T <sub>A</sub> = 25°C			BAINI	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A on D	V	1.5	3.9	5.8	1.5	6.4	
<sup>t</sup> PHL	A or B	Y	2.2	5.3	7.5	2.2	8.6	ns
<sup>t</sup> PLH	Ā/B	V	1.7	4.2	6.2	1.7	6.8	
<sup>t</sup> PHL	A/B	Y	2.3	5.5	8	2.3	9	ns
<sup>t</sup> PLH	G	V	1.6	3.8	5.9	1.6	6.5	
<sup>t</sup> PHL	G	Y	2.3	5.4	7.8	2.3	8.8	ns

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### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	36	pF

### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 3 \ ns$ ,  $t_f = 3 \ ns$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AC11157DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74AC11157DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74AC11157DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74AC11157DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74AC11157N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI
74AC11157N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI
74AC11157N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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